

Production PCB M033-1

- Name: M033-1
- Number of layers: 4 Layer-Multilayer
- Material: FR4 – 1,55mm
- Copper Thickness inner/outer: 35µm(1oz) / 35µm(1oz)
- Dimensions LxWxH: 150mm x 180mm x 1,55mm
- Surface: Chem. Nickel/Gold (Ni/Au)
- Structures /Trace clearance/
Trace width inner/outer: $\geq 0,15\text{mm}$
- Drills/VIAs: $\geq 0,25\text{mm}$
- Soldermask: Top + Bottom green
- Silkscreen: Top + Bottom white
- E-Test: Yes

Gerber Files:

- File-typ: GERBER_RS274X
- Unit: MM
- Format: 4.4

Layer Stack:

- .GTO Top Overlay
- .GTP Top Paste
- .GTS Top Solder
- .GTL Top Layer
- .GP1 Inner Layer 1
- .GP2 Inner Layer 2
- .GBL Bottom Layer
- .GBS Bottom Solder
- .GBP Bottom Paste
- .GBO Bottom Overlay
- .GM2 Board Outline, mechanical
- .txt Drills